



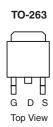
# N-Channel 100 V (D-S) 175 °C MOSFET

PRODUC	T SUMMARY	
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)
100	0.0095 at V <sub>GS</sub> = 10 V	110 <sup>a</sup>

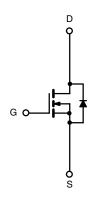
#### **FEATURES**

- TrenchFET® Power MOSFET
- New Package with Low Thermal Resistance
- 100 % R<sub>g</sub> Tested





Ordering Information: SUM110N10-09-E3 (Lead (Pb)-free)



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATI</b>	<b>NGS</b> $T_C = 25  ^{\circ}C$ , unless othe	rwise noted		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	100	V
Gate-Source Voltage		V <sub>GS</sub>	± 20	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Continuous Dunin Comment (T., 175 °C)	T <sub>C</sub> = 25 °C	_	110 <sup>a</sup>	
Continuous Drain Current ( $T_J = 175 ^{\circ}\text{C}$ )	T <sub>C</sub> = 125 °C	l <sub>D</sub>	87 <sup>a</sup>	A
Pulsed Drain Current		I <sub>DM</sub>	440	^
Avalanche Current		I <sub>AR</sub>	75	
Repetitive Avalanche Energy <sup>b</sup>	L = 0.1 mH	E <sub>AR</sub>	280	mJ
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	В	375 <sup>c</sup>	W
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	- P <sub>D</sub>	3.75	VV
Operating Junction and Storage Temperatu	ure Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RA	TINGS			
Parameter		Symbol	Limit	Unit
Junction-to-Ambient	PCB Mount (TO-263) <sup>d</sup>	R <sub>thJA</sub>	40	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.4	C/VV

#### Notes:

- a. Package limited.
- b. Duty cycle  $\leq$  1 %.
- c. See SOA curve for voltage derating.
  d. When mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	100			V
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2		4	V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μΑ
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		0.0078	0.0095	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C			0.017	Ω
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C			0.025	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A	25			S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			6700		
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		750		рF
Reverse Transfer Capacitance	C <sub>rss</sub>			280		
Total Gate Charge <sup>c</sup>	Qg			110	160	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 85 \text{ A}$		24		nC
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			24		
Gate Resistance	$R_{g}$		1.0		6.2	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20	30	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		125	200	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55	85	ns
Fall Time <sup>c</sup>	t <sub>f</sub>			130	195	
Source-Drain Diode Ratings and Cha	aracteristics 7	Γ <sub>C</sub> = 25 °C <sup>b</sup>		•		
Continuous Current	I <sub>S</sub>				110	^
Pulsed Current	I <sub>SM</sub>				240	Α
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 85 A, V <sub>GS</sub> = 0 V		1.0	1.5	V
Reverse Recovery Time	t <sub>rr</sub>			70	140	ns
Peak Reverse Recovery Charge	I <sub>RM(REC)</sub>	I <sub>F</sub> = 50 A, dl/dt = 100 A/μs		5.5	10	Α
Reverse Recovery Charge	Q <sub>rr</sub>			0.19	0.35	μC

#### Notes:

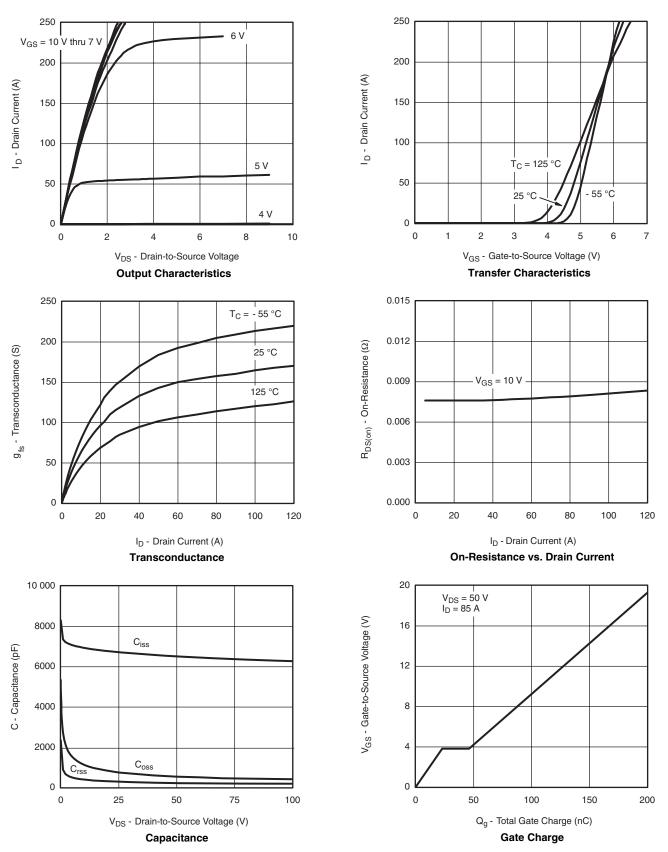
- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





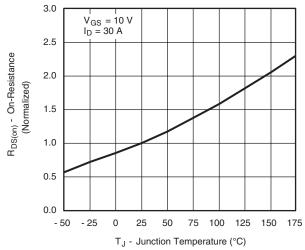
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



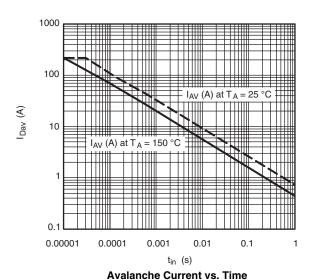
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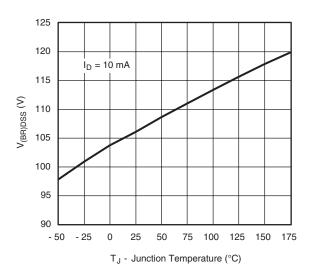
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



On-Resistance vs. Junction Temperature



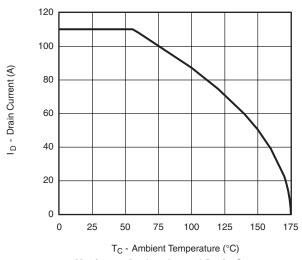
Source-Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



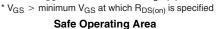
#### THERMAL RATINGS

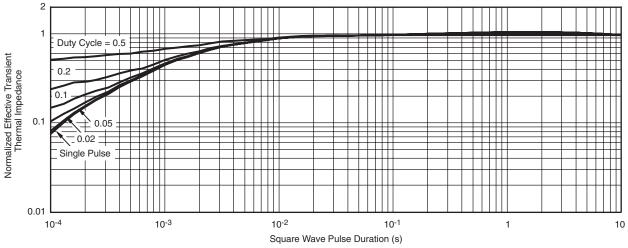


100 μs
Limited by R<sub>DS(on)\*</sub>
10 μs
1 ms
10 ms
1

1000

Maximum Avalanche and Drain Current vs. Case Temperature





Normalized Thermal Transient Impedance, Junction-to-Case

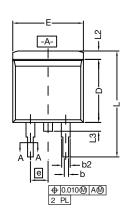
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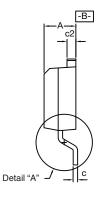
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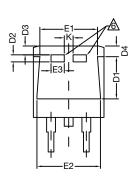


# TO-263 (D<sup>2</sup>PAK): 3-LEAD

#### **VERSION 1: FACILITY CODE = T**

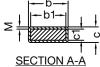








**DETAIL A (ROTATED 90°)** 



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< T		[C]	ပ
SF	CTION	1	1

#### **Notes**

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. \*: Thin lead is for SUB, SYB. Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

6. This feature is for thick lead.

		INC	HES	MILLIN	METERS
	DIM.	MIN.	MAX.	MIN.	MAX.
	Α	0.160	0.190	4.064	4.826
b		0.020	0.039	0.508	0.990
	b1	0.020	0.035	0.508	0.889
	b2	0.045	0.055	1.143	1.397
c*	Thin lead	0.013	0.018	0.330	0.457
١	Thick lead	0.023	0.028	0.584	0.711
c1	Thin lead	0.013	0.017	0.330	0.431
Ü	Thick lead	0.023	0.027	0.584	0.685
	c2	0.045	0.055	1.143	1.397
	D	0.340	0.380	8.636	9.652
	D1	0.220	0.240	5.588	6.096
	D2	0.038	0.042	0.965	1.067
	D3	0.045	0.055	1.143	1.397
	D4	0.044	0.052	1.118	1.321
	E	0.380	0.410	9.652	10.414
	E1	0.245	-	6.223	-
	E2	0.355	0.375	9.017	9.525
	E3	0.072	0.078	1.829	1.981
	е	0.100 BSC		2.54	BSC
	K	0.045	0.055	1.143	1.397
	L	0.575	0.625	14.605	15.875
	L1	0.090	0.110	2.286	2.794
	L2	0.040	0.055	1.016	1.397
	L3	0.050	0.070	1.270	1.778
	L4	0.010	BSC	0.254	BSC
	М	-	0.002	-	0.050

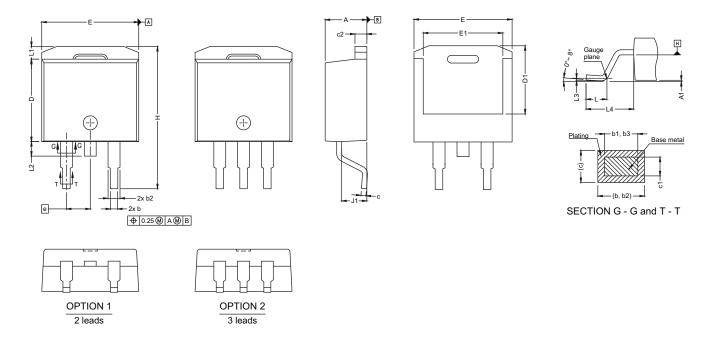
Revison: 28-Oct-2024 Document Number: 71198



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#### **VERSION 2: FACILITY CODE = N**



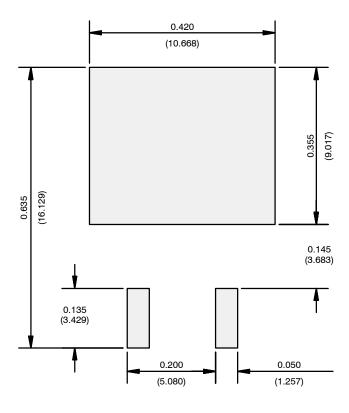
DIM.	MIN.	MAX.
A	4.36	4.56
A1	0	0.25
b	0.70	0.90
b1	0.51	0.89
b2	1.20	1.46
b3	1.17	1.37
С	0.38	0.694
c1	0.38	0.534
c2	1.19	1.34
D	8.60	9.00
D1	6.9	7.5
E	10.15	10.55
E1	8.1	8.7
е	2.54	BSC
Н	15.0	15.6
L	1.9	2.5
L1	-	1.65
L2	-	1.78
L3	0.25	5 typ.
L4	4.78	5.28
J1	2.56	2.96

DWG: 5843





## RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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